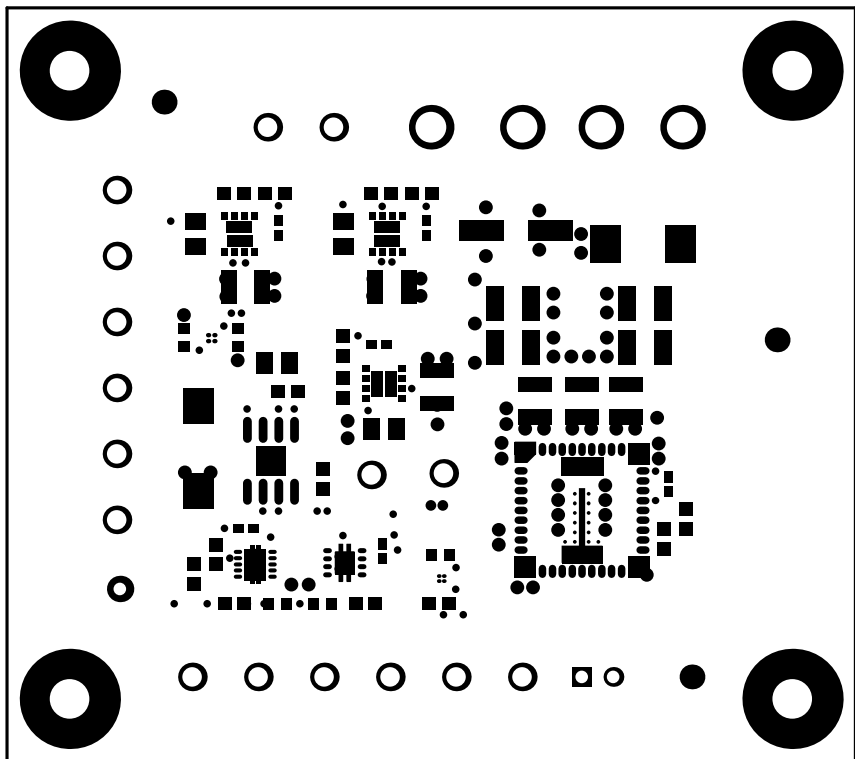


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10630	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 4/1/2015	9:34:36 AM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE

BOARD #: PMP10630

REV: B

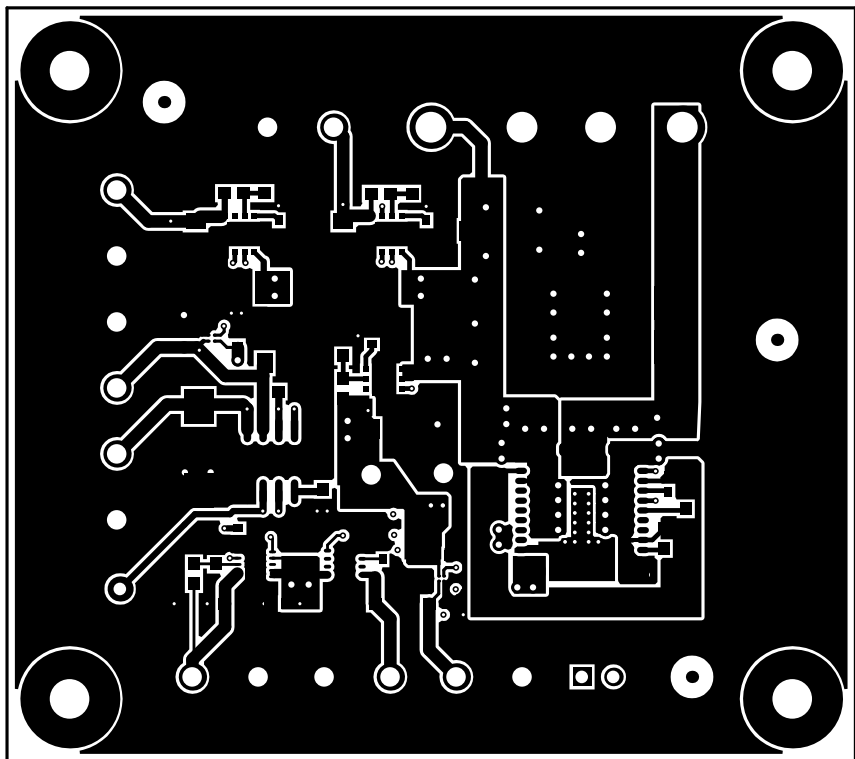
SUN REV: Not In VersionControl

LAYER NAME = Top Solder

PLOT NAME = Top Solder Mask

GENERATED : 4/1/2015 9:34:37 AM

TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE

BOARD #: PMP10630

REV: B

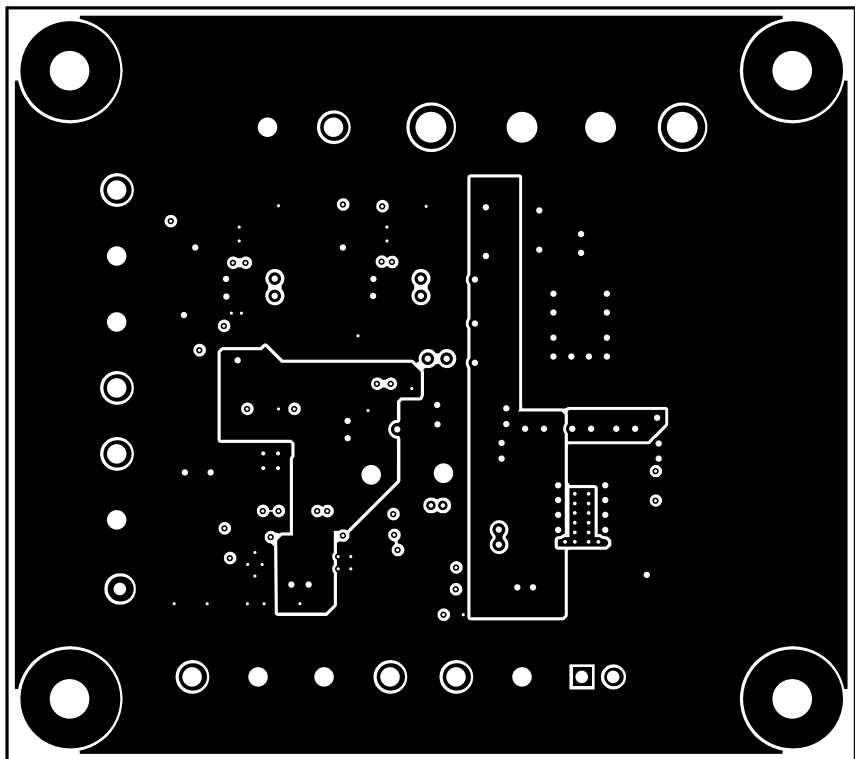
SUN REV: Not In VersionControl

LAYER NAME = Top Layer

PLOT NAME = Top Layer

GENERATED : 4/1/2015 9:34:38 AM

TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE

BOARD #: PMP10630

REV: B

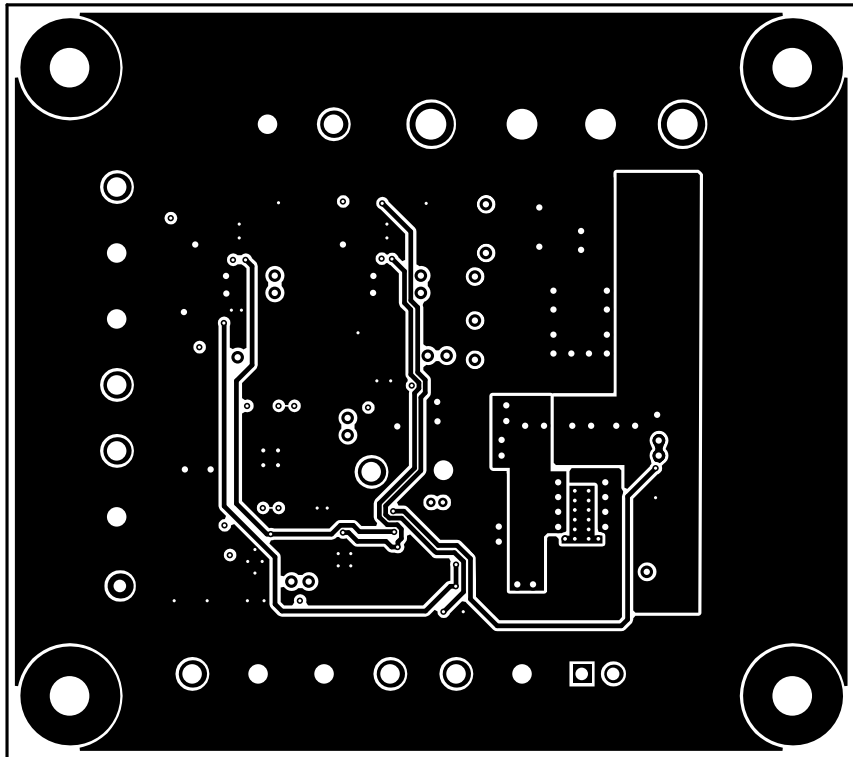
SUN REV: Not In VersionControl

LAYER NAME =

PLOT NAME = MidLayer1

GENERATED : 4/1/2015 9:34:39 AM

TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE

BOARD #: PMP10630

REV: B

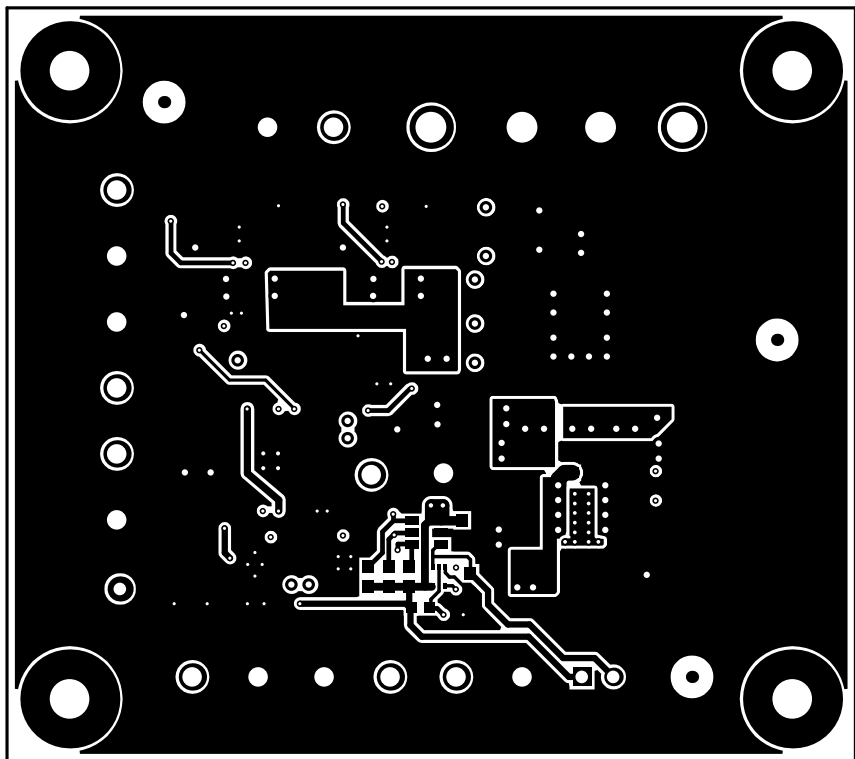
SUN REV: Not In VersionControl

LAYER NAME =

PLOT NAME = MidLayer2

GENERATED : 4/1/2015 9:34:40 AM

TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE

BOARD #: PMP10630

REV: B

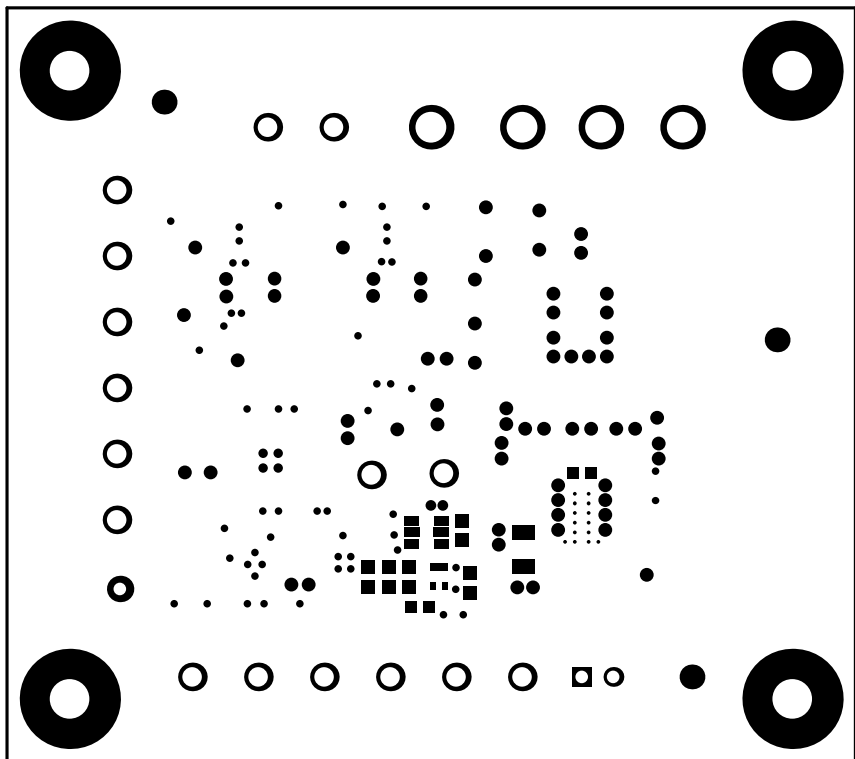
SUN REV: Not In VersionControl

LAYER NAME = Bottom Layer

PLOT NAME = Bottom Layer

GENERATED : 4/1/2015 9:34:41 AM

TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE

BOARD #: PMP10630

REV: B

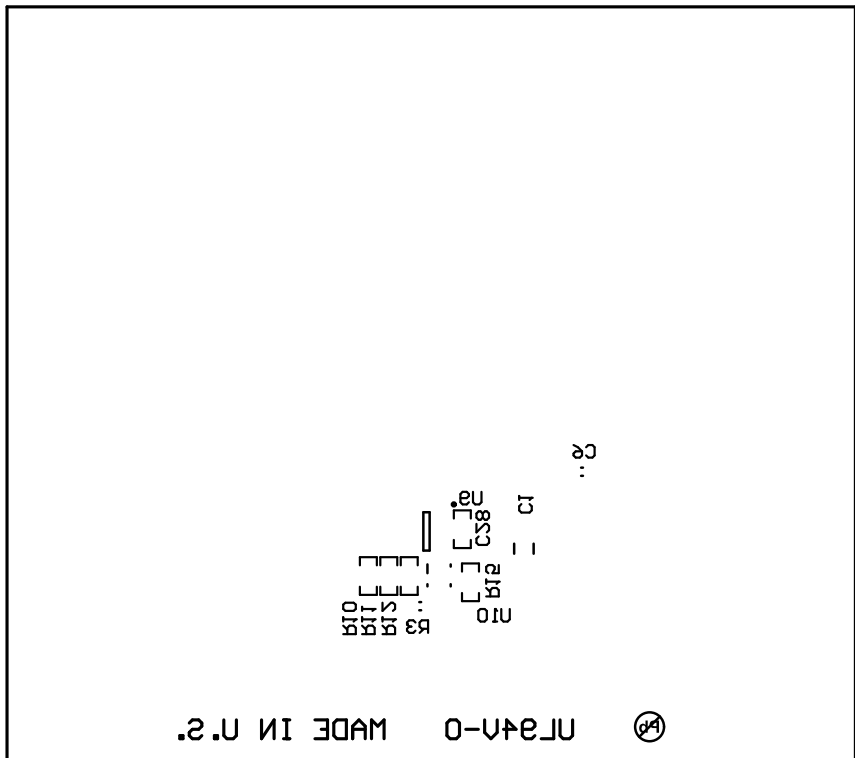
SUN REV: Not In VersionControl

LAYER NAME = Bottom Solder

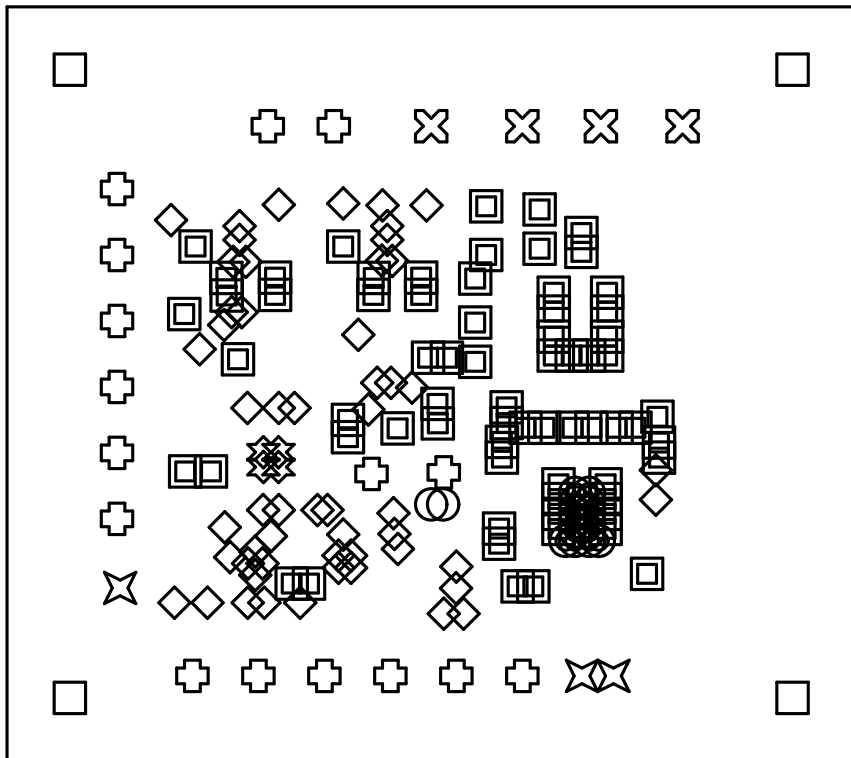
PLOT NAME = Bottom Solder Mask

GENERATED : 4/1/2015 9:34:42 AM

TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10630	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 4/1/2015	9:34:43 AM	TEXAS INSTRUMENTS



Symbol	Quantity	Finished Hole Size	Plated	Hole Type
◇	55	10.00mil (0.254mm)	PTH	Round
●	14	12.00mil (0.305mm)	PTH	Round
✱	4	12.99mil (0.330mm)	PTH	Round
○	2	15.00mil (0.381mm)	PTH	Round
■	68	20.00mil (0.508mm)	PTH	Round
✕	3	40.00mil (1.016mm)	PTH	Round
⊕	16	63.00mil (1.600mm)	PTH	Round
⊗	4	98.43mil (2.500mm)	PTH	Round
□	4	125.98mil (3.200mm)	PTH	Round
	170 Total			

ALL ARTWORK VIEWED FROM TOP SIDE

BOARD #: PMP10630

REV: B

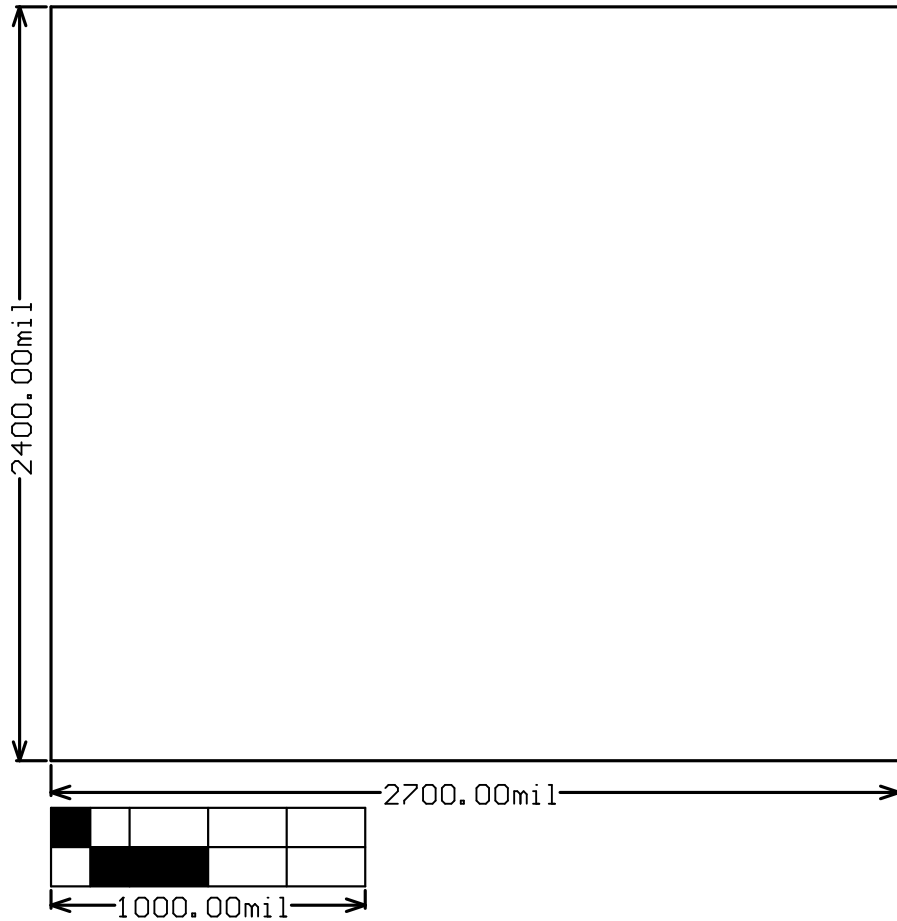
SUN REV: Not In VersionControl

LAYER NAME = Drill Drawing

PLOT NAME = Drill Drawing

GENERATED : 4/1/2015 9:34:44 AM

TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10630	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Mechanical 2			
PLOT NAME = Board Dimensions	GENERATED : 4/1/2015	9:34:45 AM	TEXAS INSTRUMENTS

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